

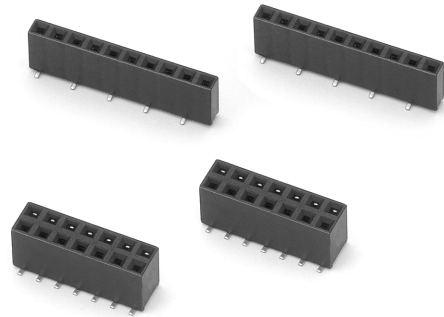
# 3490

## SMT-Buchsenleisten - RM 2,54 mm - 1-/2-reihig - Bauhöhe 7,5 mm

SMT Female Header - Pitch 2,54 mm - Single and Double Row - Height 7,5 mm

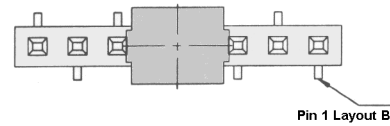
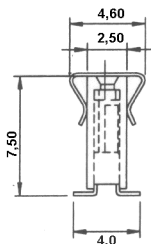
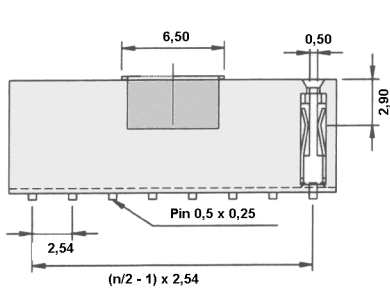
### Technische Daten / Technical Data:

|  |   |
|--|---|
| Isolierkörper<br><i>Insulator</i>                    | Thermoplastischer Kunststoff, nach UL94V0<br><i>Thermoplastic, rated UL94V0</i>                                       |
| Kontaktmaterial<br><i>Contact Material</i>           | Kontakt für Vierkantstift □ 0,635 mm, CuZn 30<br><i>Contact for Square Pin □ 0,635 mm, CuZn 30</i>                    |
| Kontaktfläche<br><i>Contact Surface</i>              | lt. Oberflächenoptionen, über Ni (1,3-2,5 µm)<br><i>acc. to options (see below), over Ni (1,3-2,5 µm)</i>             |
| Lötbarkeit<br><i>Solderability</i>                   | IEC512-12A<br><i>IEC512-12A</i>   |
| Durchgangswiderstand<br><i>Contact Resistance</i>    | ≤ 20 mOhm<br><i>≤ 20 mOhm</i>   |
| Isolationswiderstand<br><i>Insulation Resistance</i> | > 10 <sup>9</sup> Ohm<br><i>&gt; 10<sup>9</sup> Ohm</i>   |
| Spannungsfestigkeit<br><i>Test Voltage</i>           | 1000 V <sub>DC</sub><br><i>1000 V<sub>DC</sub></i>  |
| Nennspannung<br><i>Current Voltage</i>               | 250 V <sub>AC</sub><br><i>250 V<sub>AC</sub></i>  |
| Nennstrom<br><i>Current Rating</i>                   | 3 A<br><i>3 A</i>   |
| Temperaturbereich<br><i>Temperature Range</i>        | -40°C...+105°C<br><i>-40°C...+105°C</i>   |
| Verarbeitung<br><i>Processing</i>                    | Reflow-Lötverfahren; weitere Informationen in Kapitel T<br><i>Reflow-Soldering, further informations in chapter T</i> |

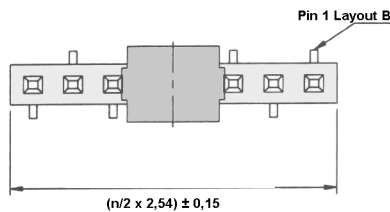


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Passende Stiftleisten Serie:  
*Mates with Pin Headers Series:*  
3531 / 3131 / 3532 / 3132 / 3533 / 3133

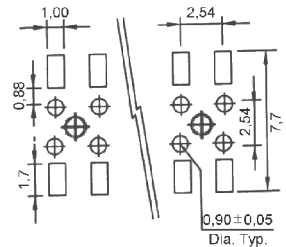
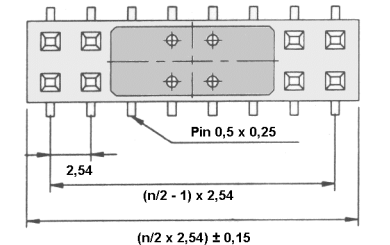
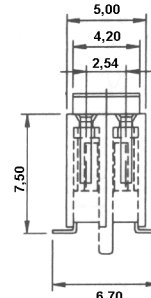
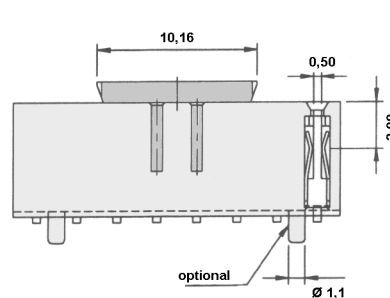


PCB - LAYOUT B1



PCB - LAYOUT B2

n = Anzahl Kontakte  
*n = No. of Contacts*



| Series | Contacts*   | Rows*   | Plating*   | Locating Peg*  | Packing*                 |
|--------|---|---|--|--|--------------------------|
| 3490   | 20  | 3   | 50   | 10   | ST                       |
|        | 04-40-pol. einreihig<br><i>single row</i><br>04-40-pol. zweireihig<br><i>double row</i> | 1 = einreihig B1<br><i>single row B1</i><br>2 = einreihig B2<br><i>single row B2</i><br>3 = zweireihig<br><i>double row</i> | 00 = vergoldet<br><i>gold plated</i><br>50 = verzinkt<br><i>tin plated</i><br>60 = sel. Au/Sn<br><i>duplex plating</i> | 00 = ohne Pos.hilfe<br><i>w/o loc. Peg</i><br>10 = mit Pos.hilfe für zweireihige Version<br><i>with loc. Peg for double row only</i> | 00<br>ST<br>PPST<br>PPTR |

### Lieferformen / Packing Options:

00 = Schüttgut ohne PP-Pad / *bulk good w/o PP-Pad*  
ST = verpackt in Stangen / *packed in tubes*  
PPST = in Stangen mit PP-Pad / *in tubes w/ PP-Pad*  
PPTR = mit PP-Pad, Tape & Reel Verpackung / *Tape & Reel Packing w/ PP-Pad*

(\* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.  
*\* Order example - To be replaced by your specifications.*)

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# Informationen zum Reflow-Lötverfahren

## Reflow-Soldering Informations

### Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflowverfahren verarbeitet werden (Maximalwerte):

| Profil Eigenschaft  | Bleifreies Lötten                 |
|---|-----------------------------------|
| Durchschnitts-Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )   | 3 °C / Sek. Max.                  |
| Vorheizen<br>- Temperatur Min ( $T_{s_{min}}$ )<br>- Temperatur Max ( $T_{s_{max}}$ )<br>- Zeit ( $t_{s_{min}}$ auf $t_{s_{max}}$ ) | 150°C<br>200°C<br>60-180 Sekunden |
| Verbleiben oberhalb:<br>- Temperatur ( $T_L$ )<br>- Zeit ( $t_L$ )  | 217°C<br>60-150 Sekunden          |
| Peak/Klassifizierung Temperatur ( $T_p$ )   | 260°C +/- 5°C                     |
| Zeit innerhalb von 5°C um die Peak-Temperatur ( $t_p$ )   | 20-40 Sekunden                    |
| Ramp-Down Rate  | 6°C / Sekunde max.                |
| Zeit von 25°C bis zur Peak-Temperatur   | 8 Minuten max.                    |

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*Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):*

| Profile Feature  | PB-Free assembly                 |
|--|----------------------------------|
| Average Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )  | 3 °C / second max.               |
| Preheat<br>- Temperature Min ( $T_{s_{min}}$ )<br>- Temperature Max ( $T_{s_{max}}$ )<br>- Time ( $t_{s_{min}}$ to $t_{s_{max}}$ ) | 150°C<br>200°C<br>60-180 seconds |
| Time maintained above:<br>- Temperature ( $T_L$ )<br>- Time ( $t_L$ )  | 217°C<br>60-150 seconds          |
| Peak/Classification Temperature ( $T_p$ )  | 260°C +/- 5°C                    |
| Time within 5°C of actual Peak Temperature ( $t_p$ )   | 20-40 seconds                    |
| Ramp-Down Rate   | 6°C / second max.                |
| Time 25°C to Peak Temperature  | 8 minutes max.                   |

Empfohlenes Reflow-Lötprofil:

*Recommended Reflow-Soldering profile:*



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